

Figure 01a - Ceramic Chip Carrier (Perspective)

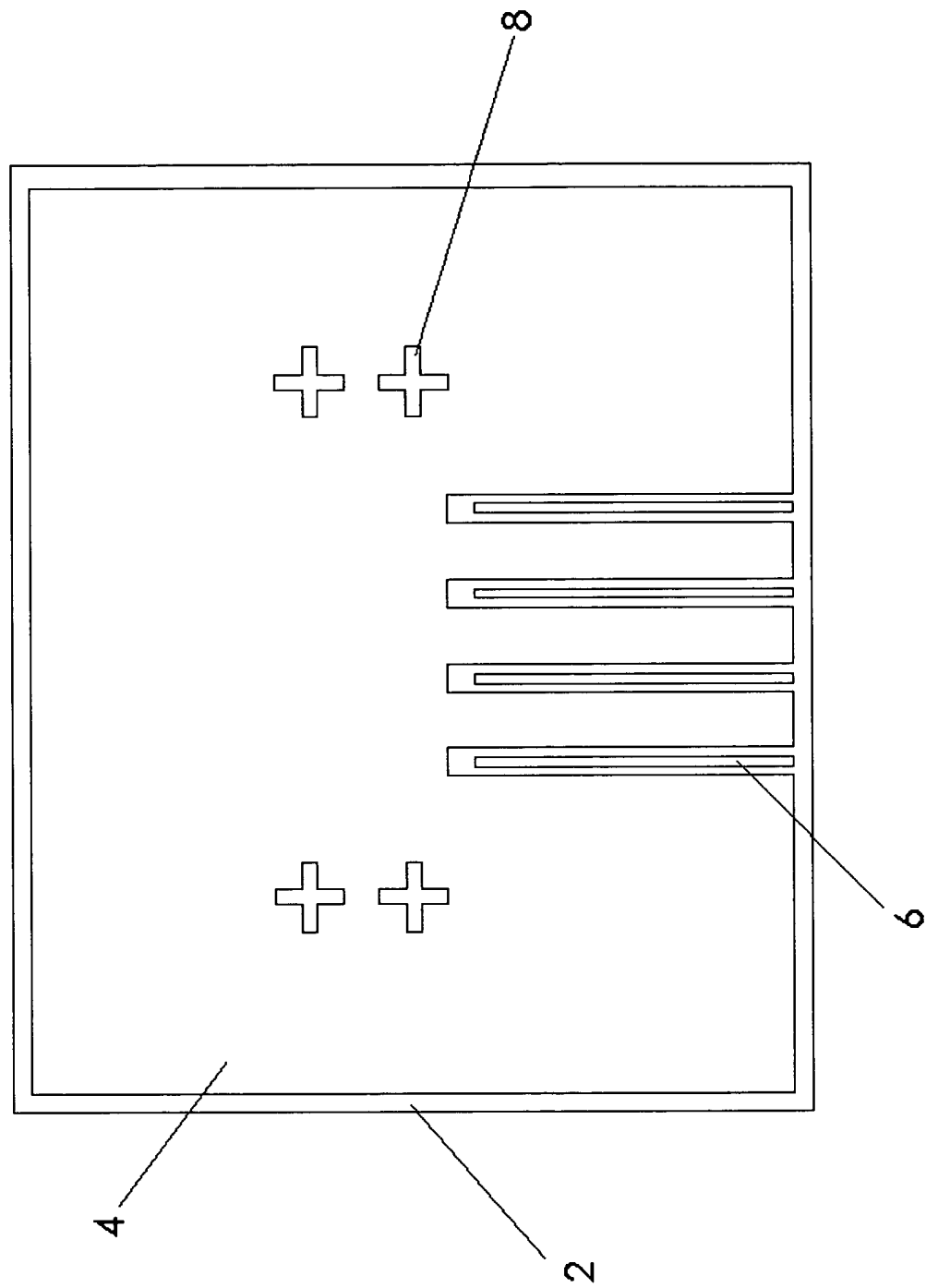


Figure 01b - Ceramic Chip Carrier (Top)

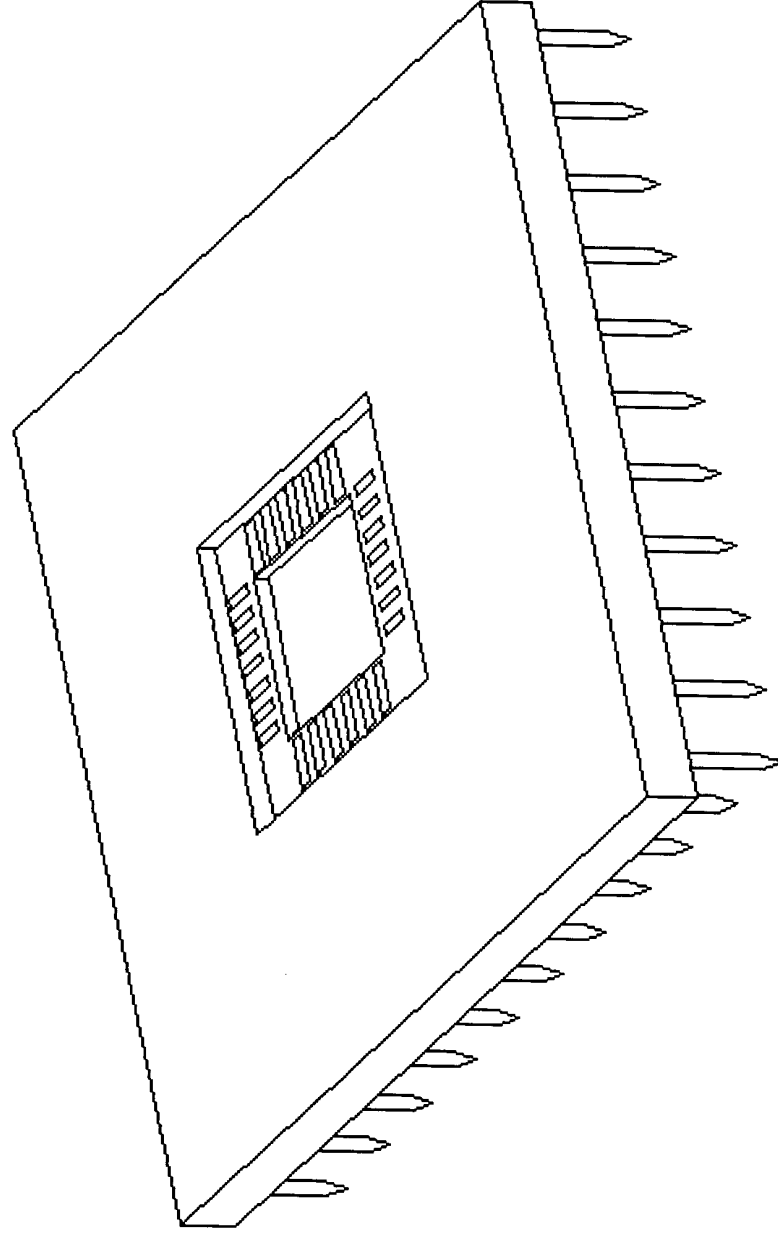


Figure 01c - Standard Pin Grid Array (PGA) (Perspective)

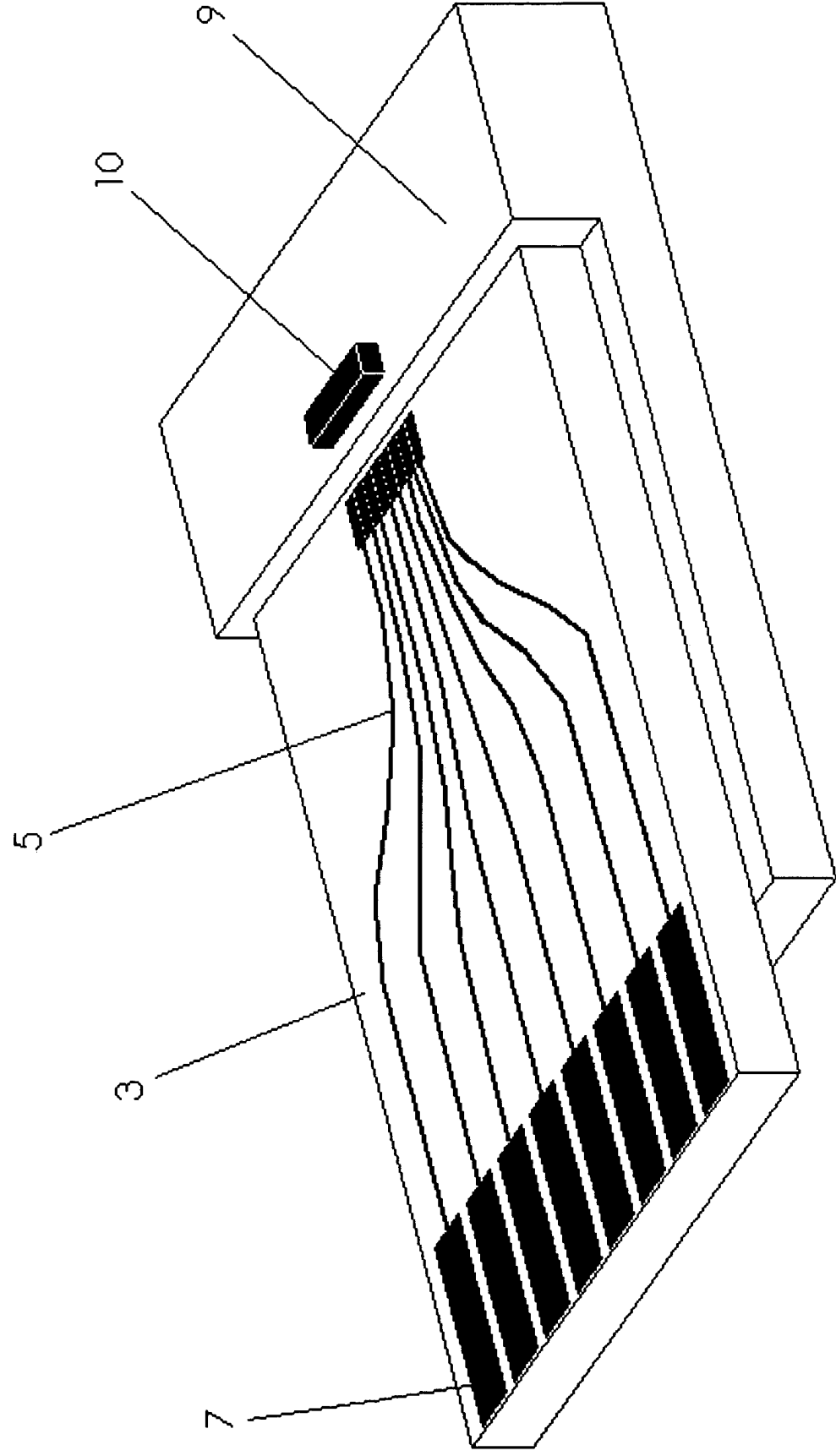


Figure 01d - Custom PCB Package (Perspective)

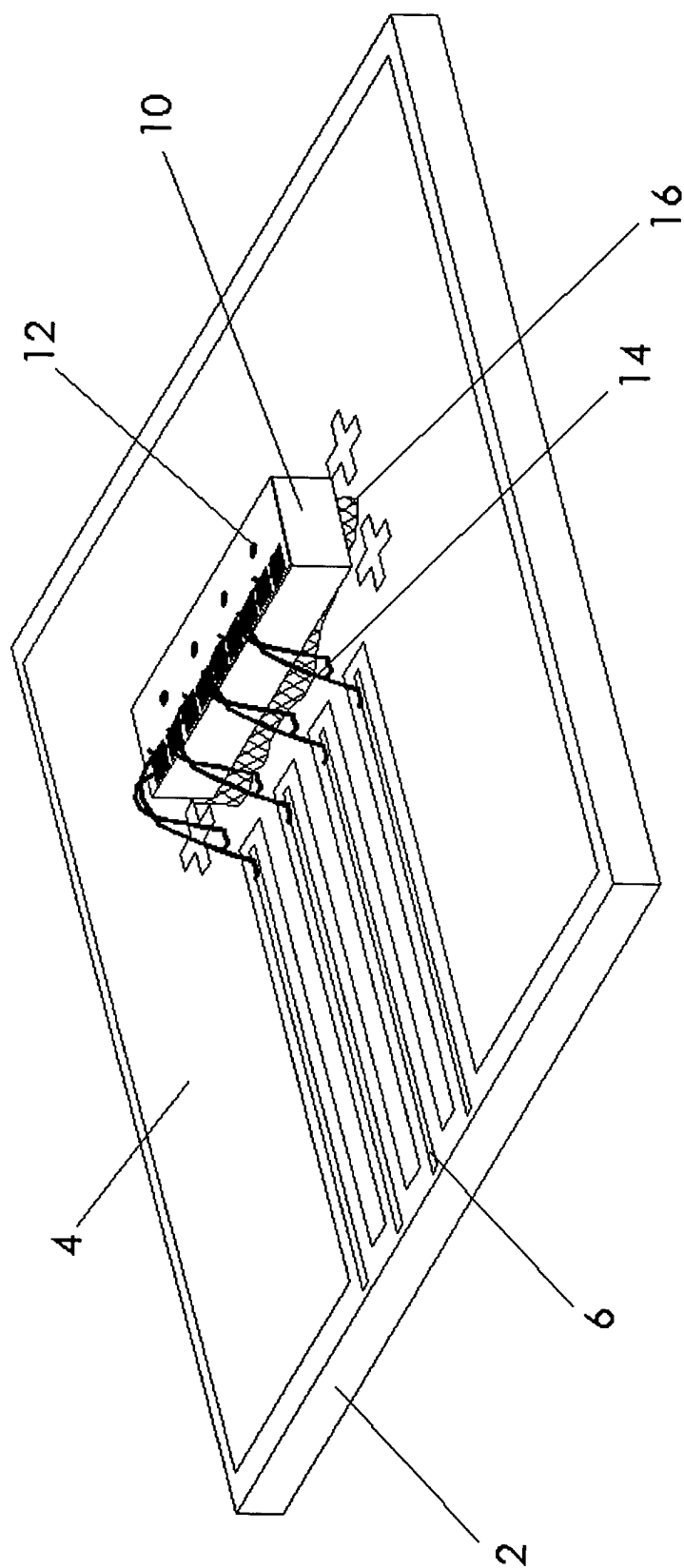


Figure 02a - Optoelectronic Chip Epoxied and Wirebonded to Carrier (Perspective)

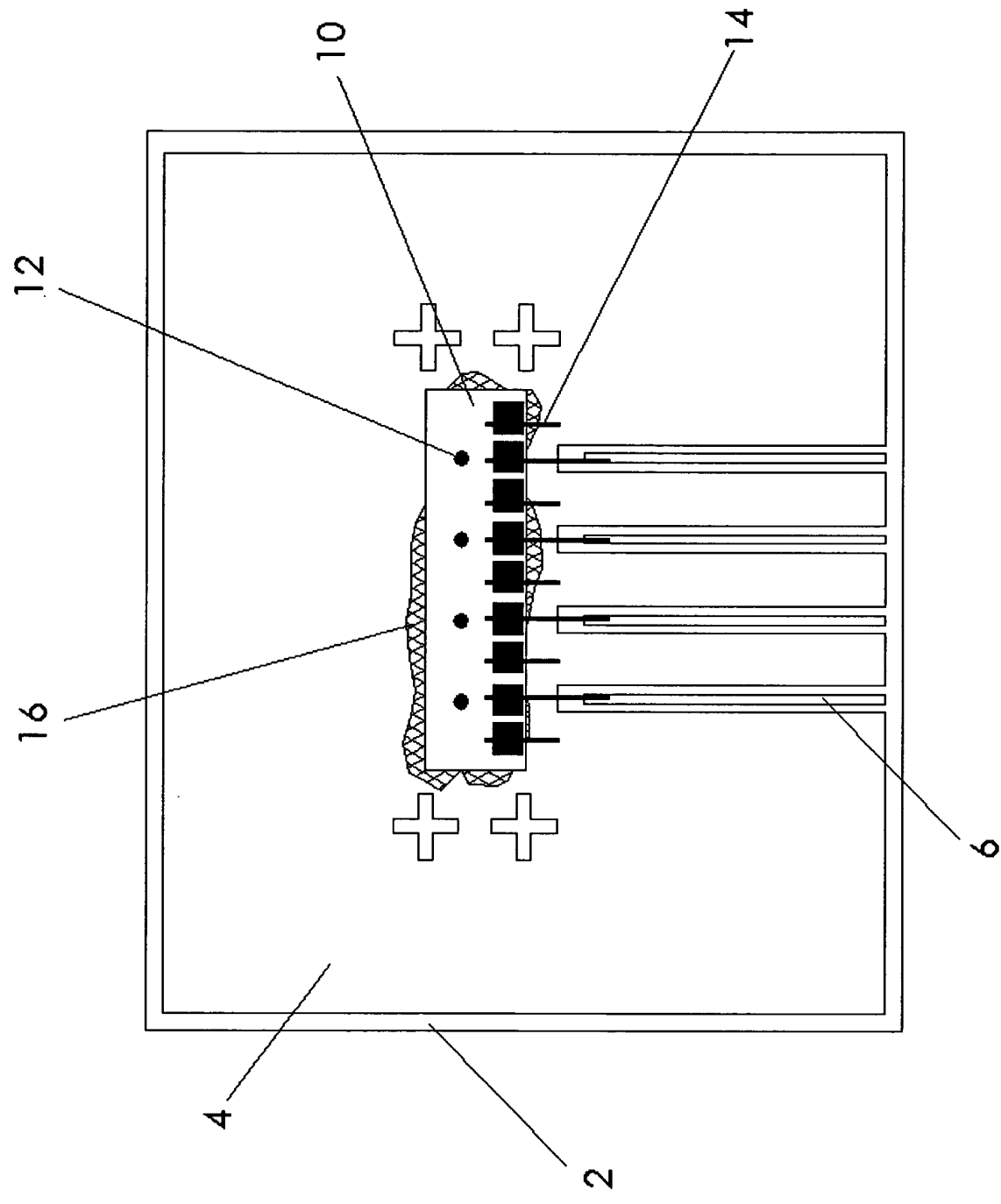


Figure 02b - Optoelectronic Chip Epoxied and Wirebonded to Carrier (Top)

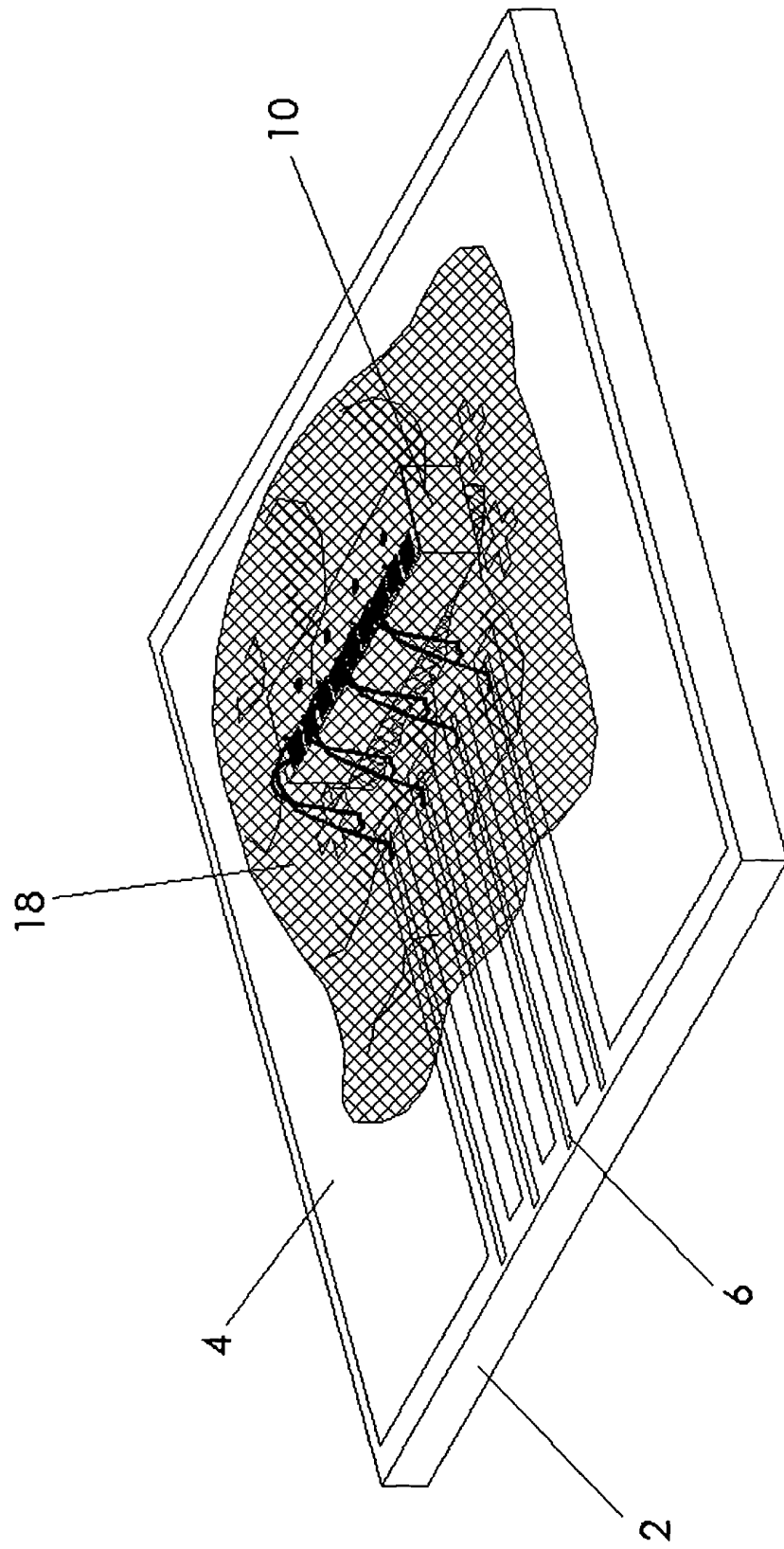


Figure 03a - Bump of Transparent Epoxy over Optoelectronic Chip (Perspective)

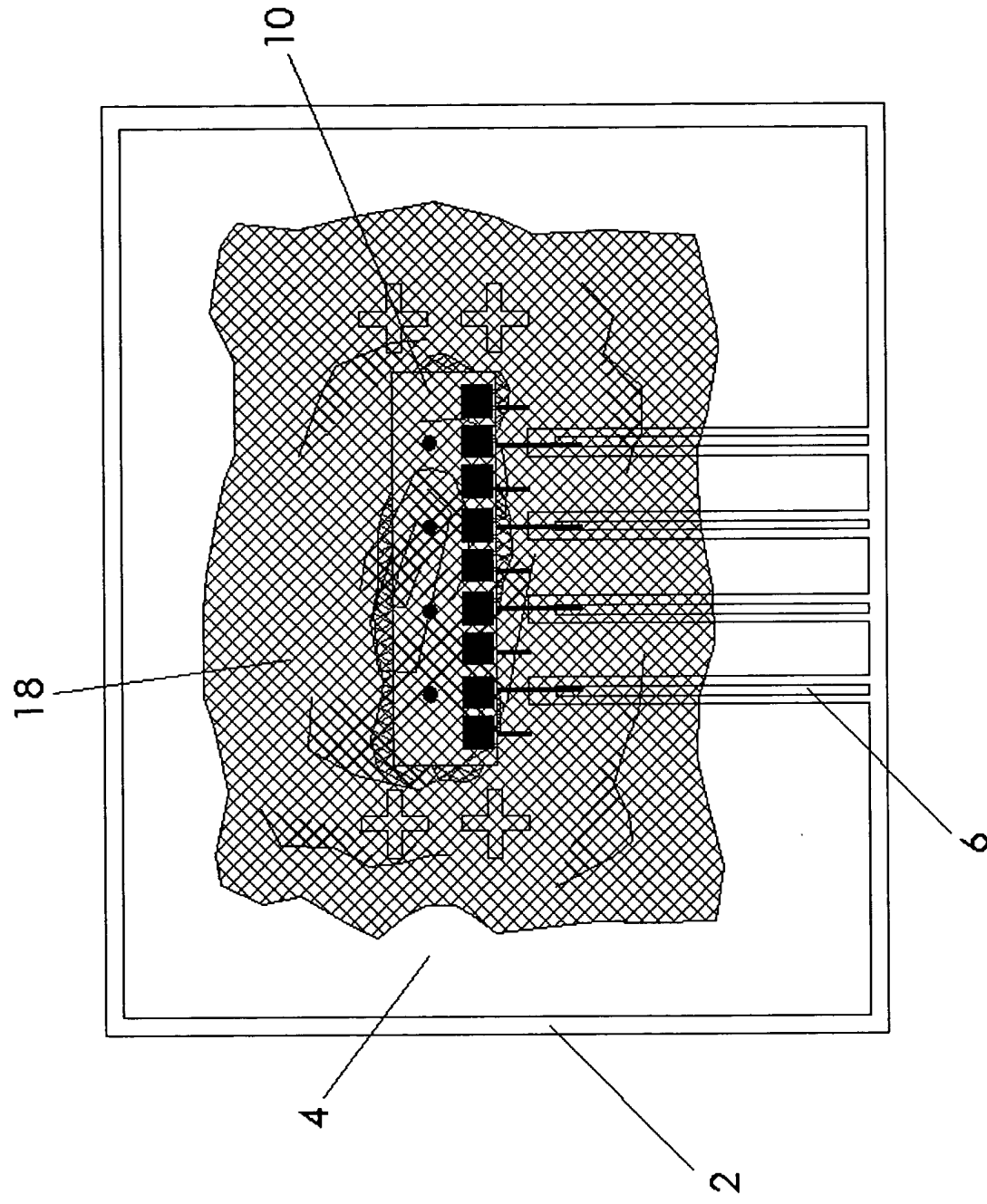


Figure 03b - Bump of Transparent Epoxy over Optoelectronic Chip (Top)



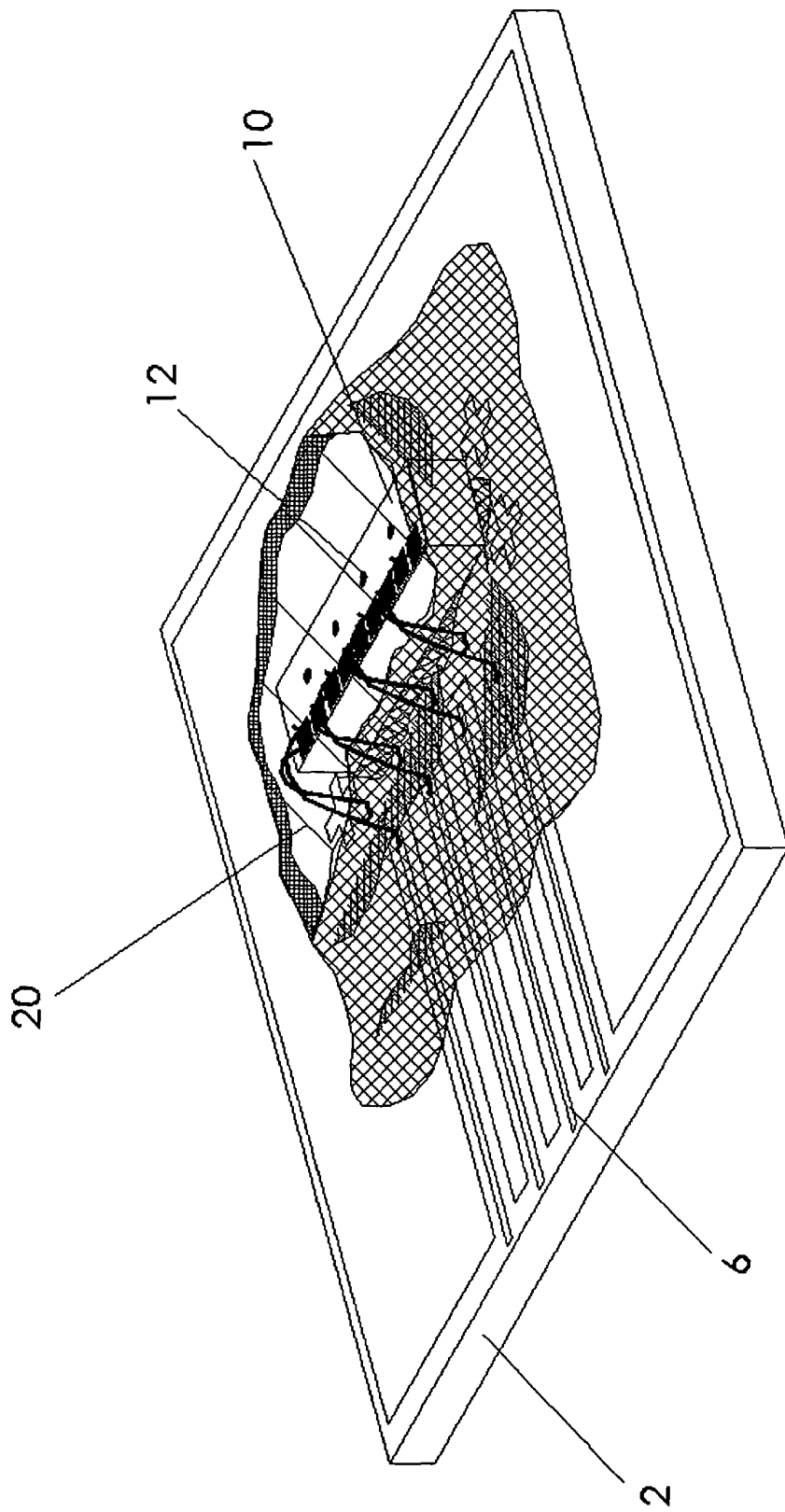


Figure 04a - Flat Polished Transparent Epoxy (Perspective)

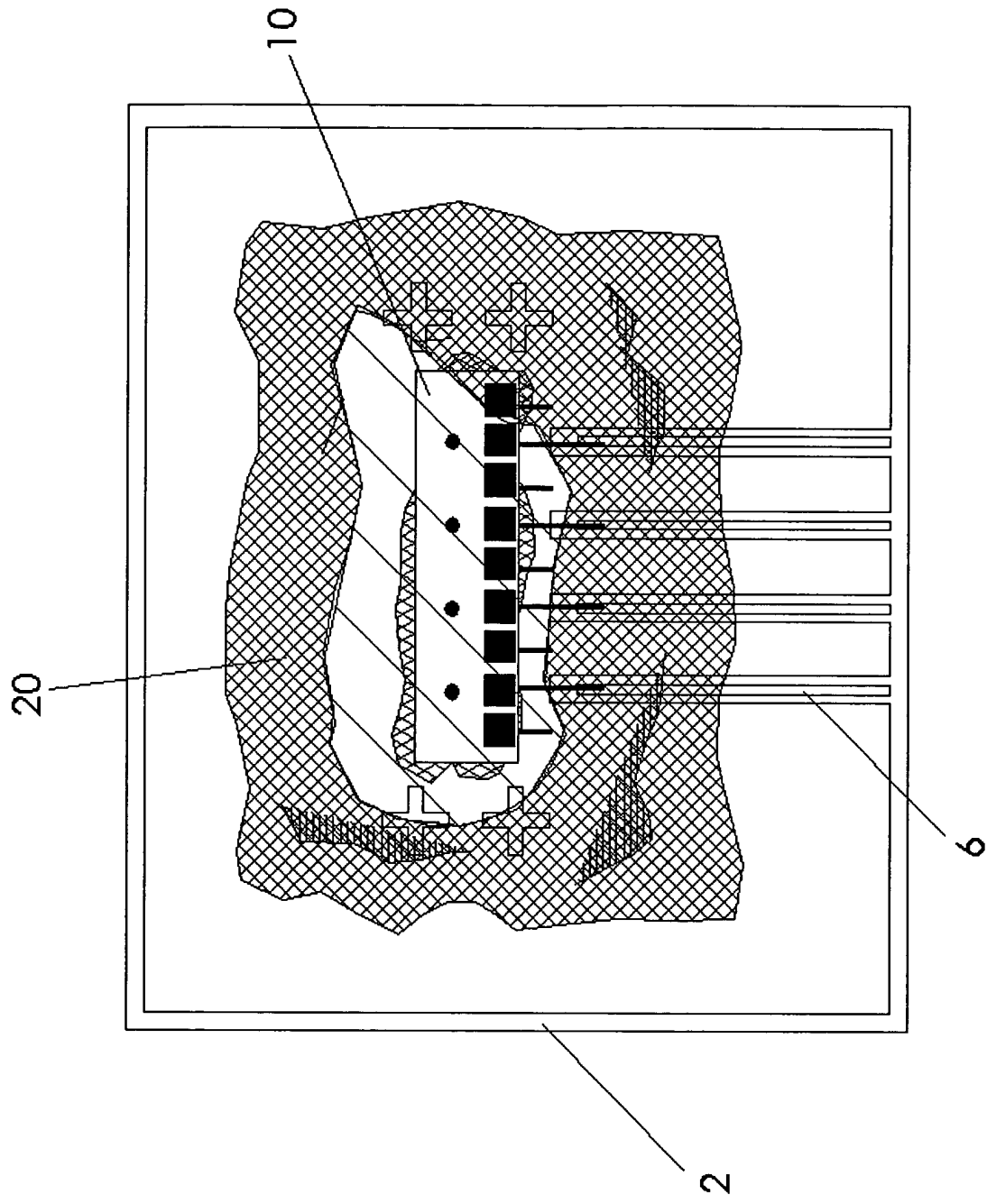


Figure 04b - Flat Polished Transparent Epoxy (Top)

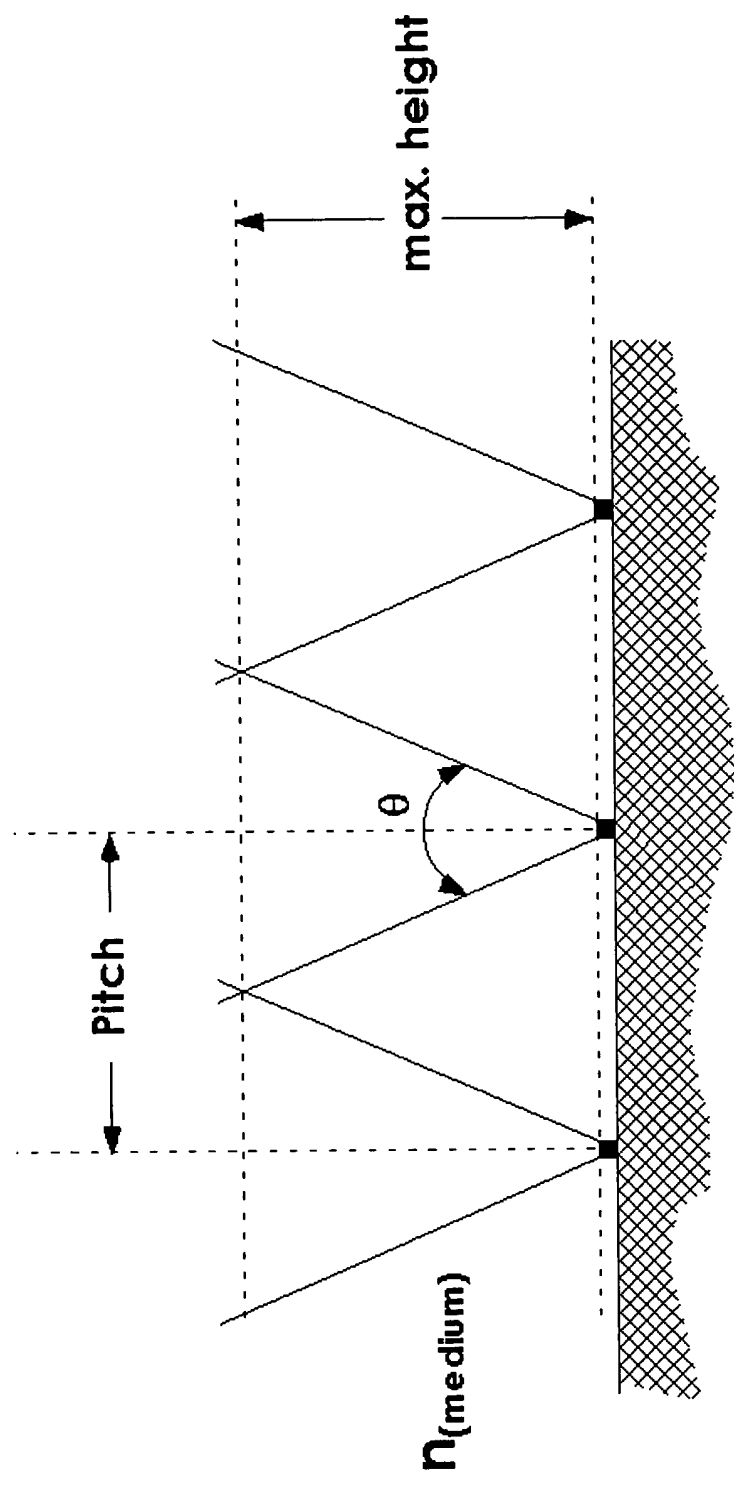


Figure 05 - Geometry for Divergence of Laser to determine Thickness

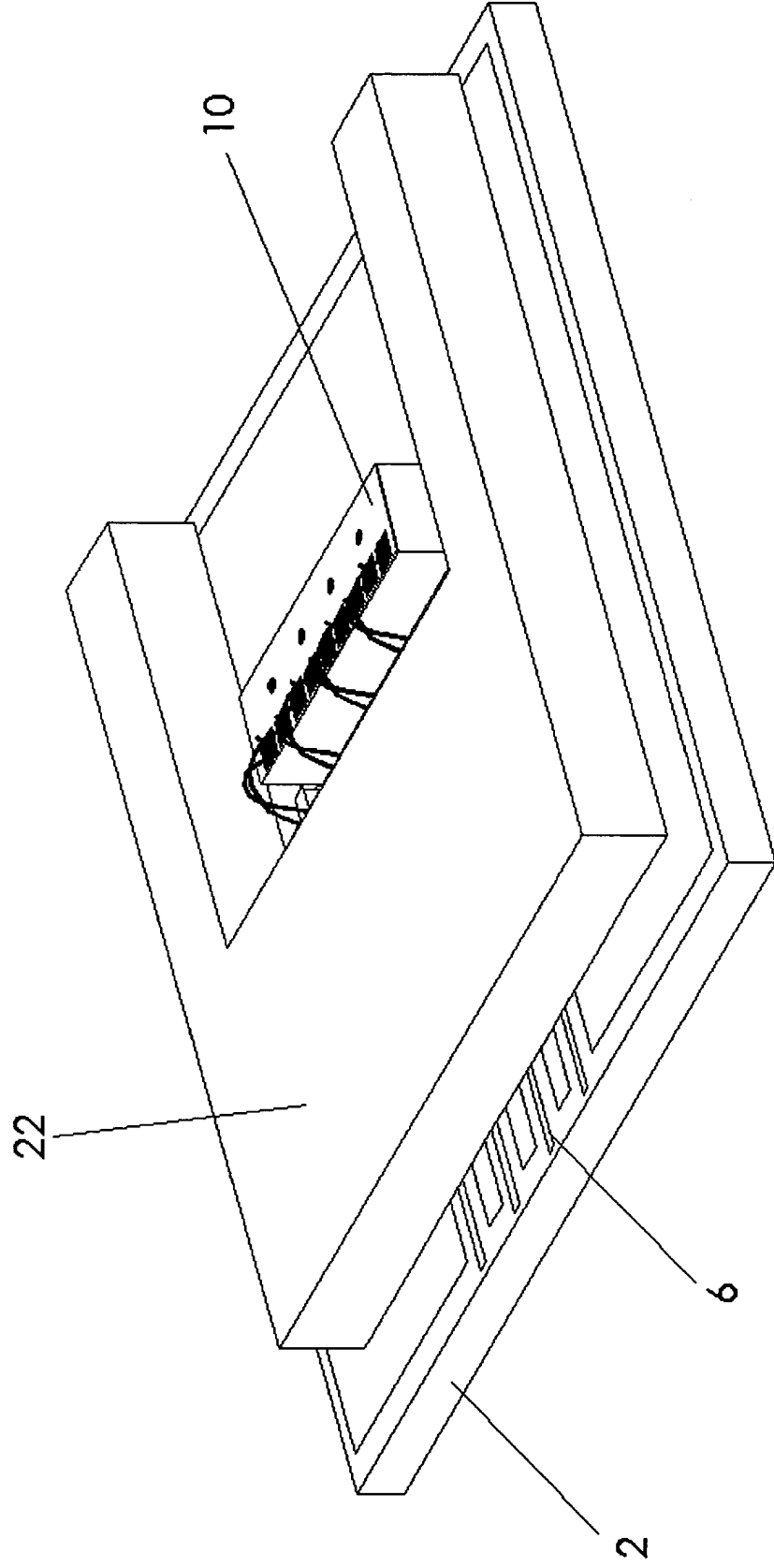


Figure 06a - Optoelectronic Chip and Carrier with Spacer Plate (Perspective)

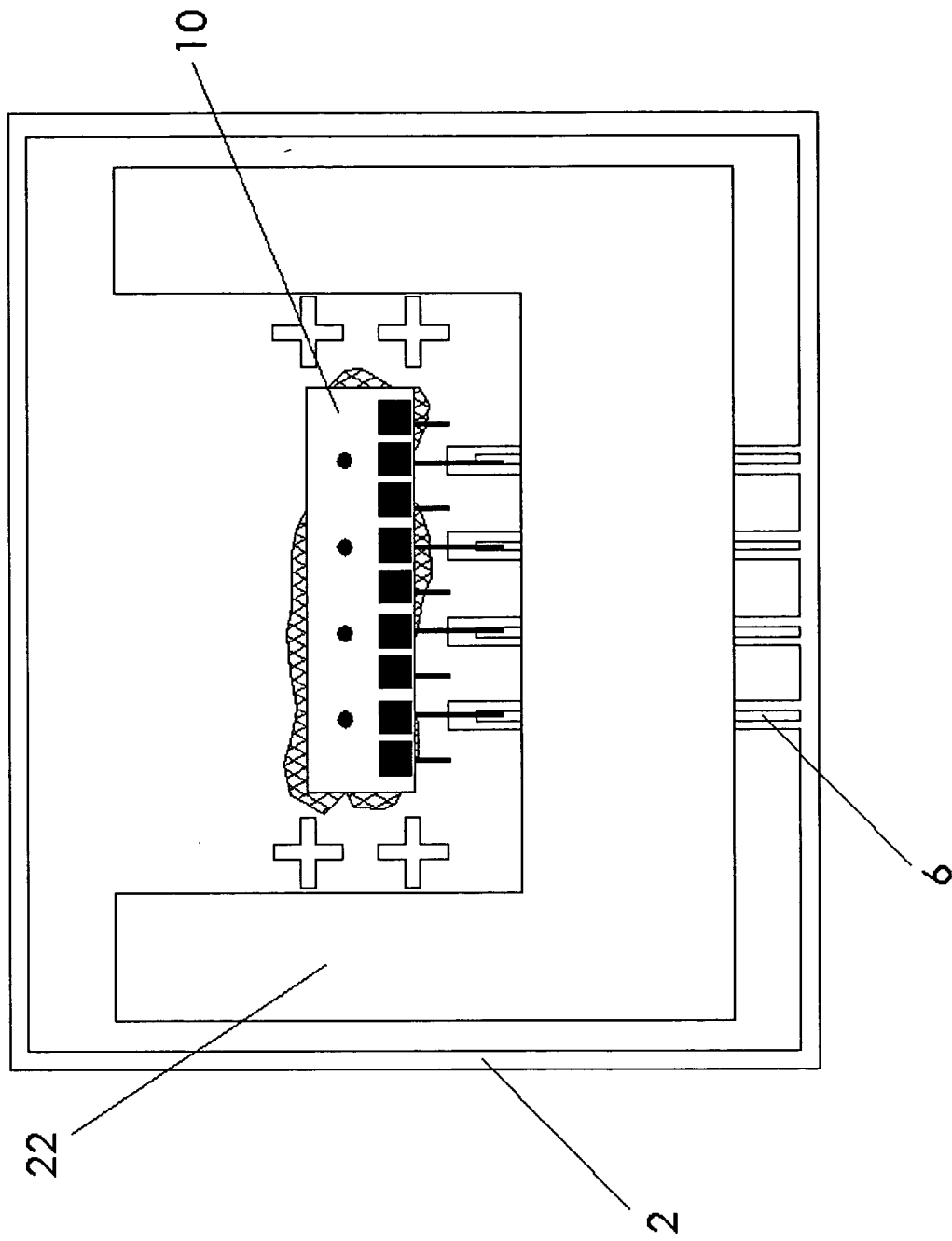


Figure 06b - Optoelectronic Chip and Carrier with Spacer Plate (Top)

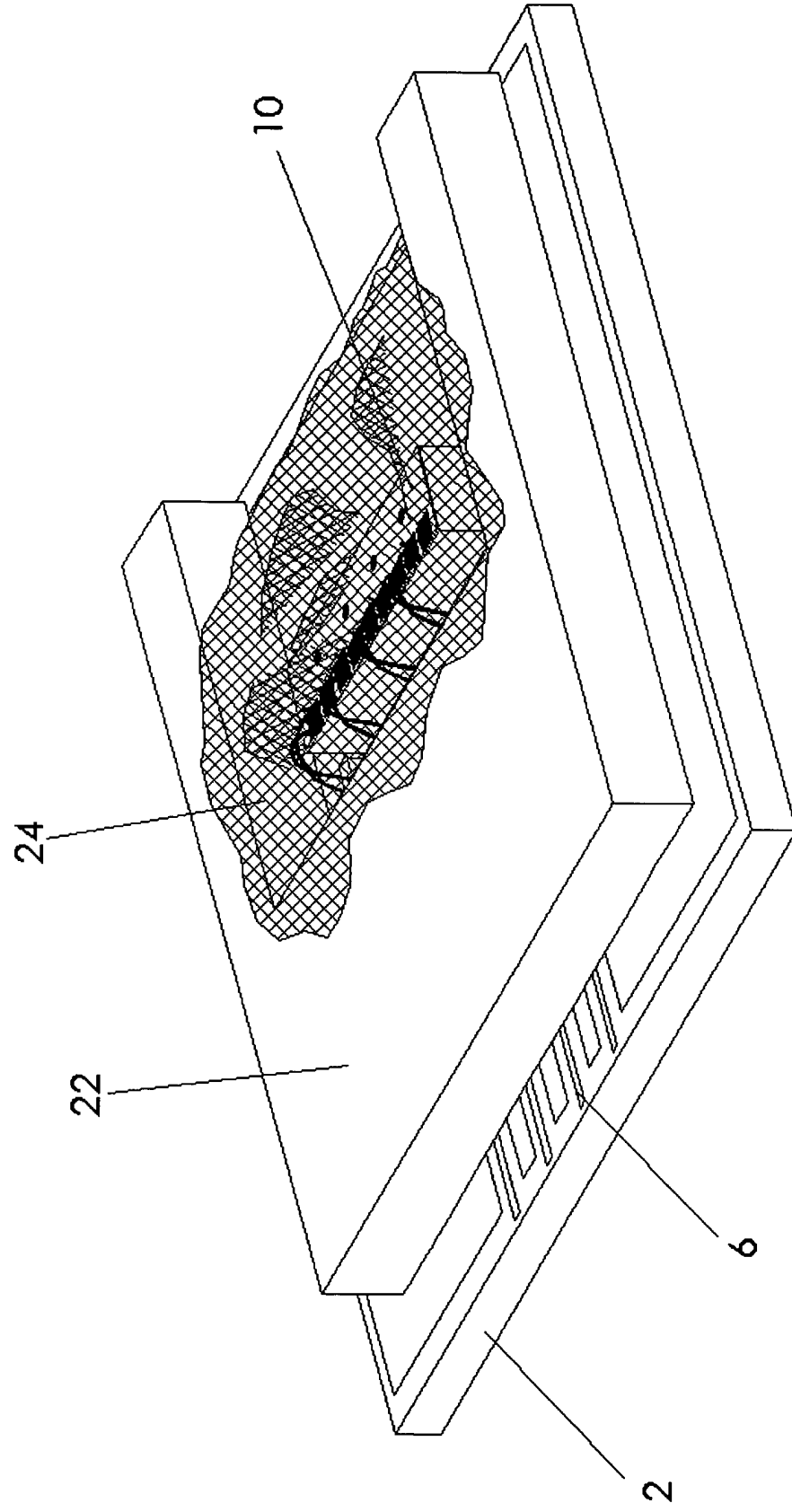


Figure 07a - Transparent Epoxy over Optoelectronic Chip (Perspective)

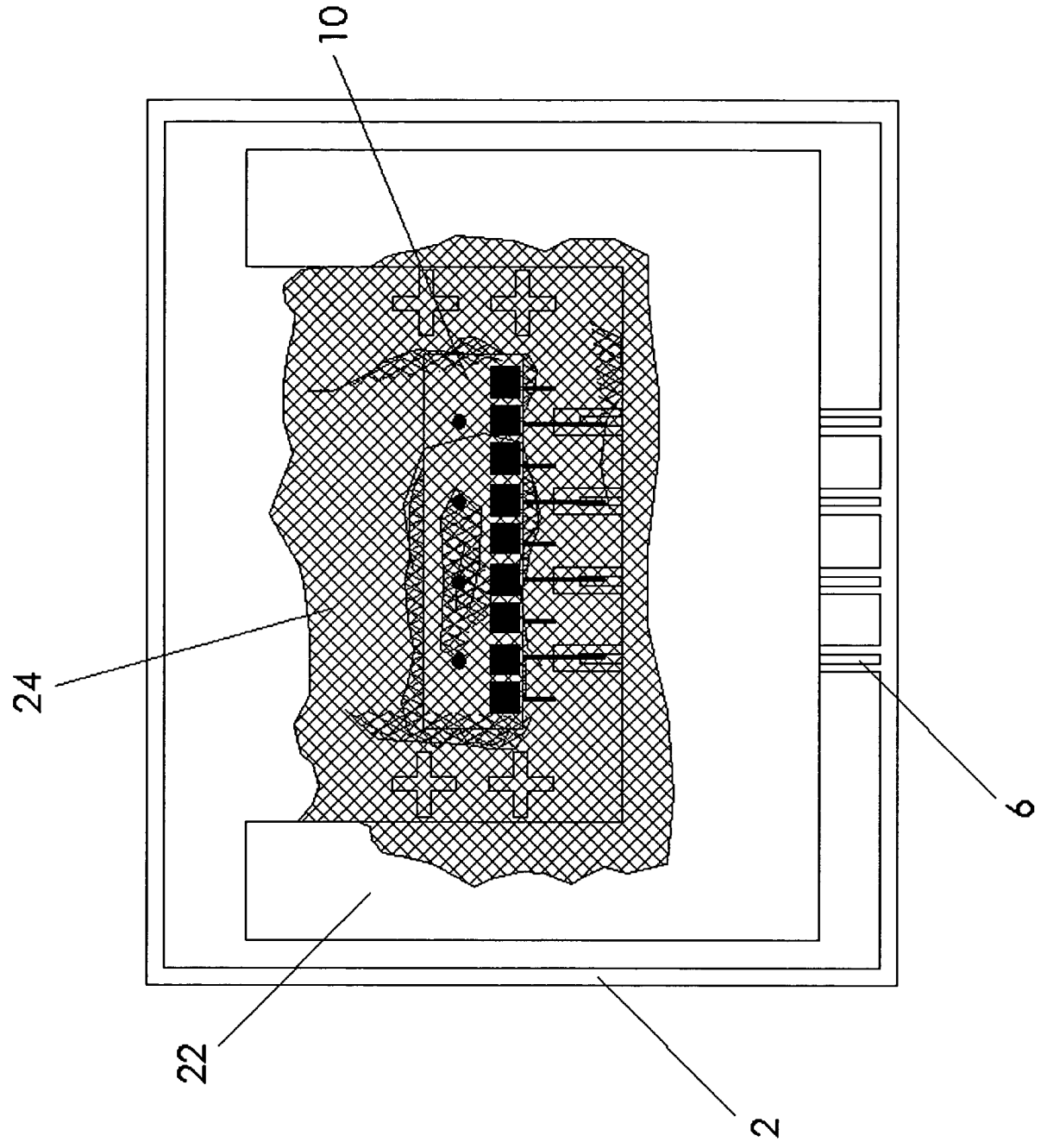


Figure 07b - Transparent Epoxy over Optoelectronic Chip (Top)

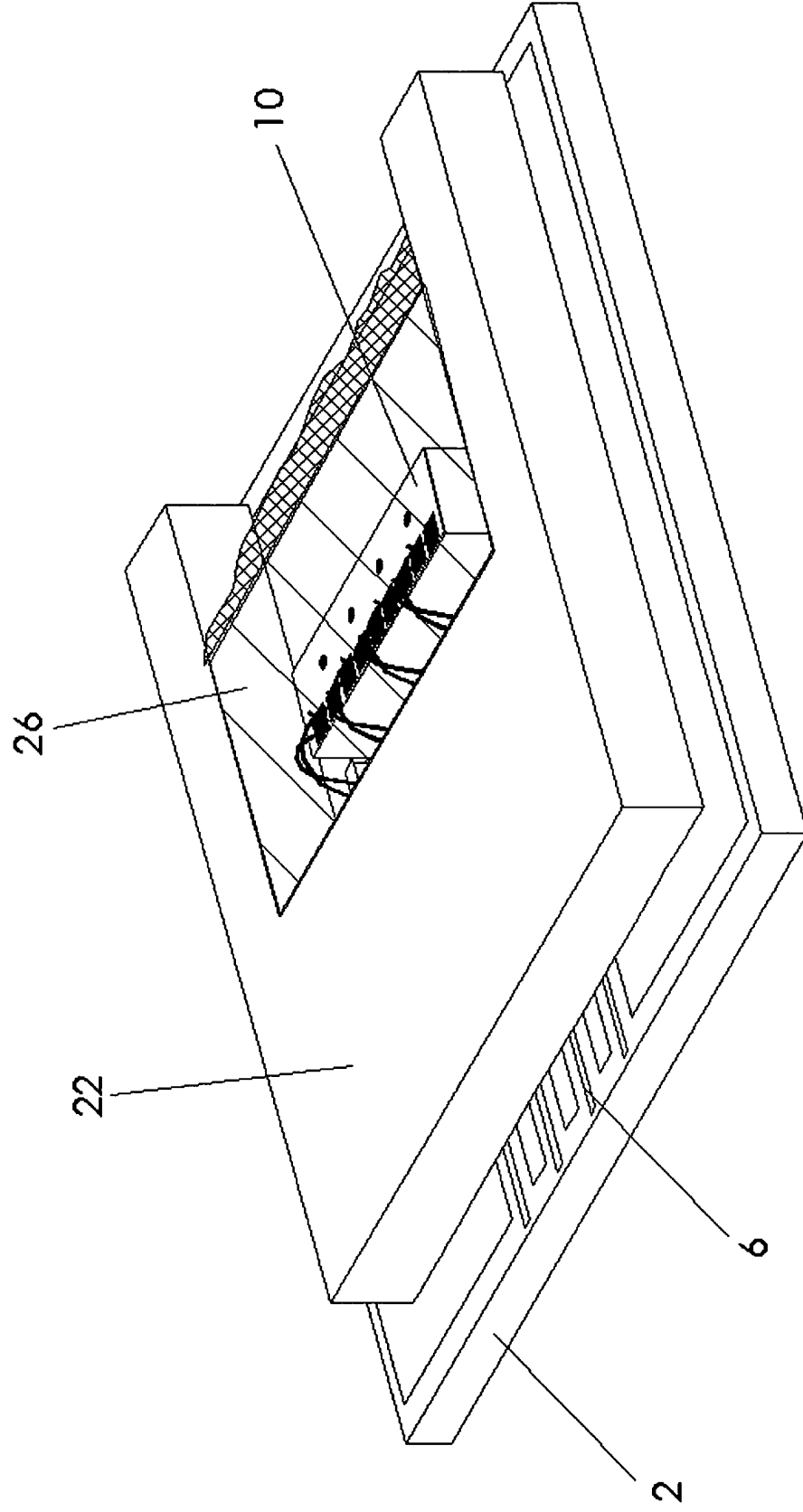


Figure 08a - Flat Polish of the Transparent Epoxy (Perspective)



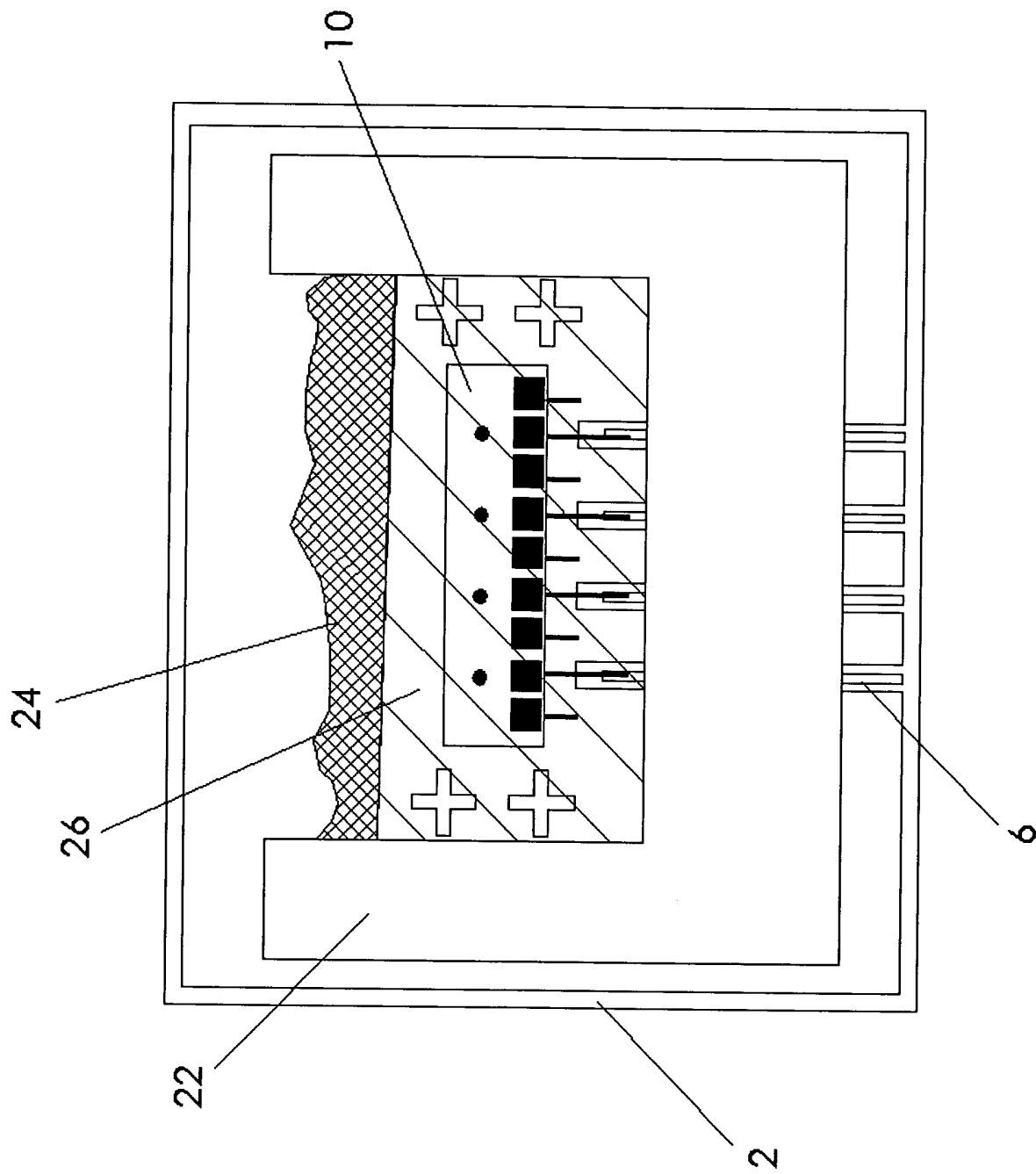


Figure 08b - Flat Polish of the Transparent Epoxy (Top)

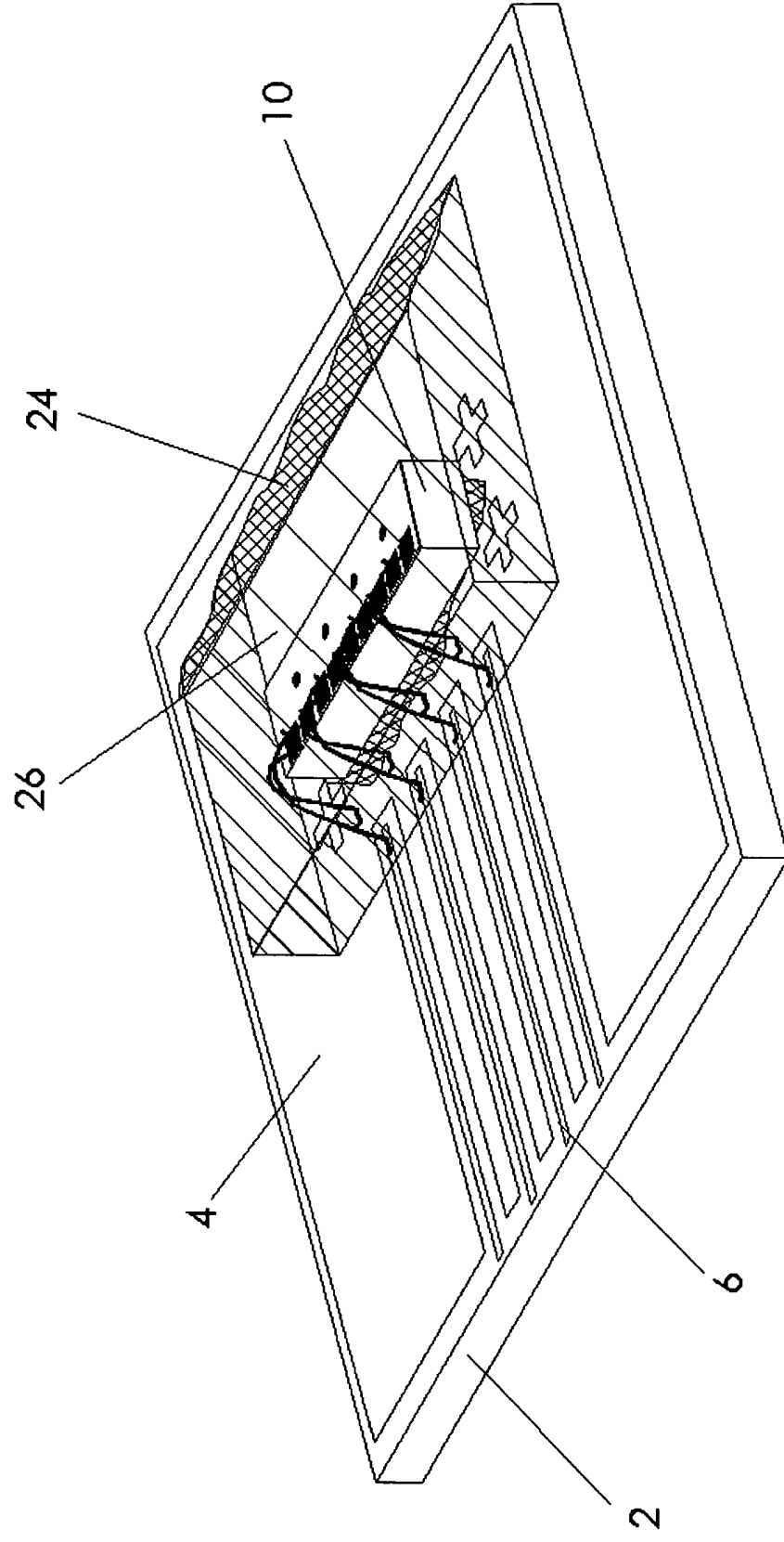


Figure 09a - Optional Removal of Spacer Plate (Perspective)

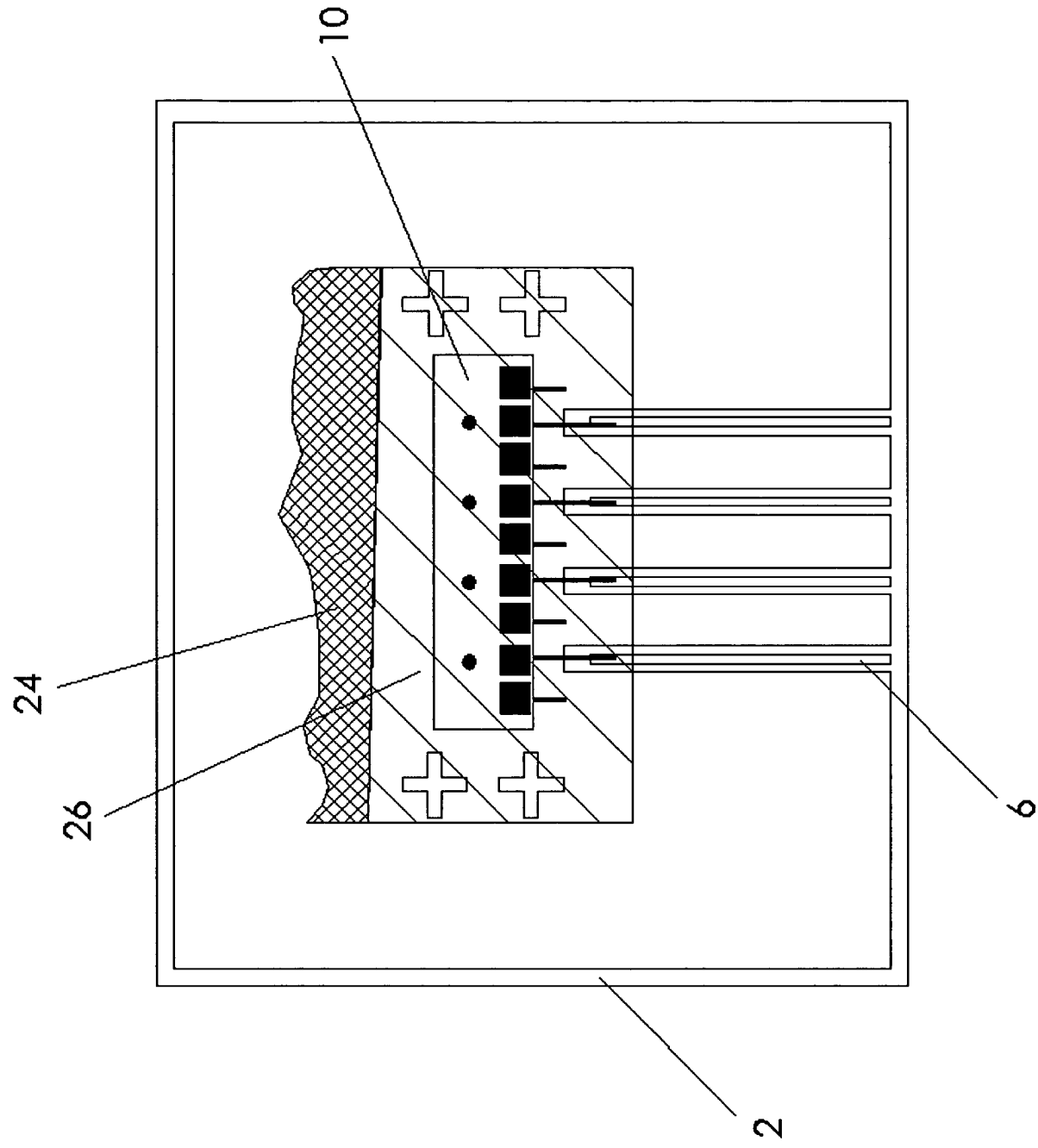


Figure 09b - Optional Removal of Spacer Plate (Top)